

HVL375CM

Variable Capacitance Diode for VCO

REJ03G0228-0200 Rev.2.00 Mar 10, 2006

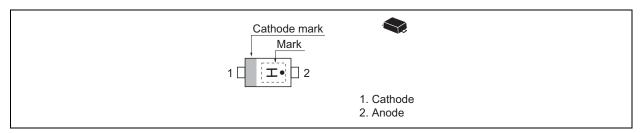
Features

- Narrow terminal Capacitance deviation.
- Low series resistance. ($r_s = 1.1 \Omega \text{ max}$)
- Good C-V linearity.
- Thin Extremely small Flat Lead Package (TEFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code	
HVL375CM	Н	TEFP	PUSF0002ZA-A	

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Reverse voltage	V_R	10	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	−55 to +125	°C

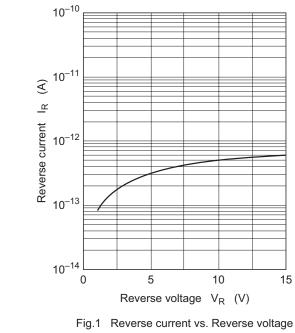
Electrical Characteristics

 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _{R1}	_	_	10	nA	V _R = 10 V
	I _{R2}	_	_	100		V _R = 10 V, Ta = 60°C
Capacitance	C ₁	15.0	_	16.5	pF	V _R = 1 V, f = 1 MHz
	C ₃	5.0		6.0		V _R = 3 V, f = 1 MHz
	C ₄	3.3	_	4.0		V _R = 4 V, f = 1 MHz
Capacitance ratio	n	4.0	_	_	_	C ₁ / C ₄
Series resistance	r _S	_	_	1.1	Ω	V _R = 2 V, f = 470 MHz

Note: For TEFP package, the material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

Main Characteristic



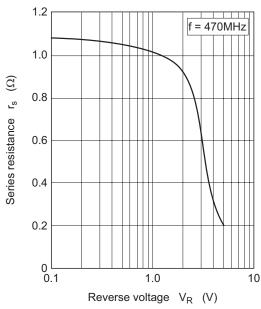


Fig.3 Series resistance vs. Reverse voltage

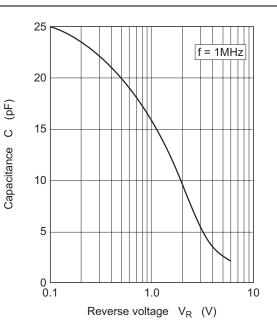
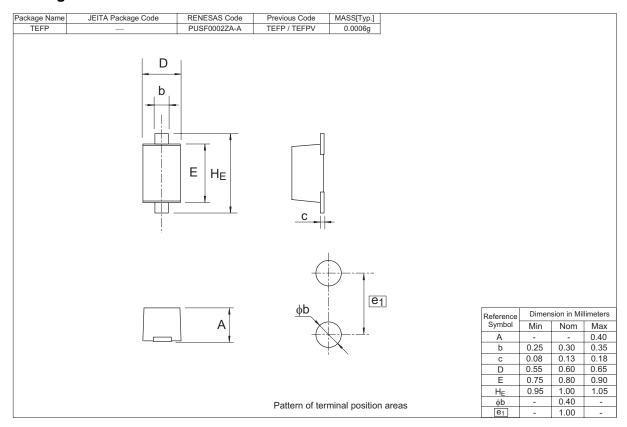


Fig.2 Capacitance vs. Reverse voltage

Package Dimensions



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Renesas Technology Europe Limited
Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K.
Tel: <44> (1628) 585-100, Fax: <44> (1628) 585-900

Renesas Technology (Shanghai) Co., Ltd. Unit 204, 205, AZIACenter, No.1233 Lujiazui Ring Rd, Pudong District, Shanghai, China 200120 Tel: <86> (21) 5877-1818, Fax: <86> (21) 6887-7898

Renesas Technology Hong Kong Ltd.
7th Floor, North Tower, World Finance Centre, Harbour City, 1 Canton Road, Tsimshatsui, Kowloon, Hong Kong Tel: <852> 2265-6688, Fax: <852> 2730-6071

Renesas Technology Taiwan Co., Ltd. 10th Floor, No.99, Fushing North Road, Taipei, Taiwan Tel: <886> (2) 2715-2888, Fax: <886> (2) 2713-2999

Renesas Technology Singapore Pte. Ltd.
1 Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632 Tel: <65> 6213-0200, Fax: <65> 6278-8001

Renesas Technology Korea Co., Ltd. Kukje Center Bldg. 18th Fl., 191, 2-ka, Hangang-ro, Yongsan-ku, Seoul 140-702, Korea Tel: <82> (2) 796-3115, Fax: <82> (2) 796-2145

Renesas Technology Malaysia Sdn. Bhd
Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No.18, Jalan Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia Tel: <603> 7955-9390, Fax: <603> 7955-9510

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